

**SINGULATION METHODS AND SUBSTRATES
FOR USE WITH SAME**

Abstract of the Disclosure

5 A circuit board substrate assembly includes a generally planar circuit board substrate material having a longitudinal axis extending along a length of the substrate material between a first end and a second end thereof. The circuit board substrate material further has a first edge and a second edge extending along the length of the circuit board substrate material between the first end and the second end. A plurality of 10 openings are defined in the substrate material. Each opening extends between a first distance from the first edge of the circuit board substrate and a second distance from the second edge of the circuit board substrate. Further, each opening separates adjacent circuit forming regions lying along the longitudinal axis and has first and second opposing end portions. The first end portions of each opening lie along a first 15 singulation axis of the substrate material parallel to the longitudinal axis and the second end portions of each opening lie along a second singulation axis of the substrate material parallel to the longitudinal axis. Removing interconnect material along the first singulation axis and second singulation axis provide for singulation of the circuit forming regions and any circuits thereof.

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